Businesses & Products

Semiconductor Components

Ceramic Packages & Substrates

High-reliability ceramic packages and substrates help to miniaturize components used in smartphones, fiber optics, automotive electronics (such as headlight LEDs), and a wide range of other applications. Kyocera utilizes its broad expertise in materials, processing, and design technologies to ensure unparalleled substrate and package performance.

Ceramic Surface-Mount Packages for Electronic Devices

Kyocera’s ultra-small ceramic surface-mount packages for crystal oscillators and other components help to miniaturize smart devices while enhancing their performance.

Ceramic Packages for Image Sensors

Ceramic packages for image sensors help create smaller camera modules with higher performance.

Optical Components

Kyocera supports today’s broadband internet with components such as fiber-optic connectors and laser-ribbon packages that protect signal devices and ensure high data speeds.

Ceramic Packages for LEDs

The excellent thermal conductivity and reliability of Kyocera’s ceramics make them ideal for packaging LEDs used in applications ranging from residential lighting to vehicle headlights.

Multilayer Ceramic Substrates for Automotive ECUs

Kyocera’s compact ECU substrates are used in automotive powertrain systems, where they provide high circuit density with excellent heat resistance, heat dissipation and reliability.

Epoxy Encapsulation Materials

Kyocera offers new epoxy materials for transfer- and compression-molding processes that can create a vast array of lightweight, mass-produced goods.

Die-Attach Pastes

Conductive pastes for semiconductors, LEDs, power devices, and electronic components help meet growing performance requirements. Examples include nano-sintered metal pastes and high thermal conductive pastes.

Varnishes

Our flame-resistant varnishes are designed to reduce environmental impact while facilitating a new level of power and efficiency in electric motors — including those used in the latest electric vehicles and industrial equipment.

Organic Packages & Printed Wiring Boards

The rapid advancement of information and communication technologies (ICT) and the expansion of the Internet demand electronic devices with better functionality and performance. Kyocera’s organic multilayer packages and printed wiring boards help meet this demand.

Flip-Chip Packages

These fine-pitch multilayer packages employ the latest advances in micro-wiring and low-profile multilayer technology. They support better functionality and performance in servers, routers and mobile communication devices.

Build-up Wiring Boards

These wiring boards are widely used in PCs, mobile devices, and other products that employ high-density surface-mounted boards.

High-Density Multilayer Printed Circuit Boards

These high-performance circuit boards are used in high-end servers and telecommunications systems, where large-scale motherboards and backplane boards may require up to 50 layers.

Organic Materials

Our other business domains extend to a wide range of industrial fields, such as digital equipment, automotive manufacturing and energy, based on our organic material technology.

Epoxy Encapsulation Materials for Semiconductors

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